

IN THE CLAIMS

Please amend the claims as follows:

Claim 1 (Original): A multilayer printed wiring board in which an interlayer insulation layer and a conductive layer are formed on a multilayer core substrate composed of front and rear conductive layers and at least a conductive layer as an inner layer and electric connection is performed through via holes,

at least one of the sum of the thicknesses of the power source conductive layers in said multilayer core substrate and the sum of the thicknesses of the grounding conductive layers is larger than the thickness of the conductive layer on the interlayer insulation layer.

Claim 2 (Original): The multilayer printed wiring board according to claim 1 wherein assuming that the sum of the thicknesses of the power source conductive layers in said multilayer core substrate is α_1 and the thickness of the conductive layer on the interlayer insulation layer is α_2 , the relation between α_1 and α_2 is $\alpha_2 < \alpha_1 \leq 40\alpha_2$.

Claim 3 (Original): The multilayer printed wiring board according to claim 1 wherein assuming that the sum of the thicknesses of the grounding conductive layers in said multilayer core substrate is α_3 and the thickness of the conductive layer on the interlayer insulation layer is α_2 , the relation between α_3 and α_2 is $\alpha_2 < \alpha_3 \leq 40\alpha_2$.

Claim 4 (Original): The multilayer printed wiring board according to claim 1 wherein assuming that the sum of the thicknesses of the power source conductive layers in said multilayer core substrate is α_1 and the thickness of the conductive layer on the interlayer insulation layer is α_2 , the relation between α_1 and α_2 is $1.2\alpha_2 \leq \alpha_1 \leq 40\alpha_2$.

Claim 5 (Original): The multilayer printed wiring board according to claim 1 wherein assuming that the sum of the thickness of the grounding conductive layer in said multilayer core substrate is α_3 and the thicknesses of the conductive layers on the interlayer insulation layer is α_2 , the relation between α_3 and α_2 is $1.2\alpha_2 \leq \alpha_3 \leq 40\alpha_2$.

Claim 6 (Original): The multilayer printed wiring board according to claim 1 wherein assuming that the sum of the thicknesses of power source conductive layers in said multilayer core substrate is α_1 and the thickness of the conductive layer on the interlayer insulation layer is α_2 , the relation between α_1 and α_2 is $\alpha_2 < \alpha_1 \leq 40\alpha_2$ and assuming that the sum of the thicknesses of the grounding conductive layers in said multilayer core substrate is α_3 , the relation between α_3 and said α_2 is $\alpha_2 < \alpha_3 \leq 40\alpha_2$.

Claim 7 (Original): The multilayer printed wiring board according to claim 1 wherein assuming that the sum of the thicknesses of the power source conductive layers in said multilayer core substrate is α_1 and the thickness of the conductive layer on the interlayer insulation layer is α_2 , the relation between α_1 and α_2 is $1.2\alpha_2 \leq \alpha_1 \leq 40\alpha_2$ and assuming that the sum of the thicknesses of the grounding conductive layers in said multilayer core substrate is α_3 , the relation between α_3 and said α_2 is $1.2\alpha_2 \leq \alpha_3 \leq 40\alpha_2$.

Claim 8 (Currently Amended): The multilayer printed wiring board according to ~~any one of claims 1-7~~ claim 1 wherein the thickness of the conductive layer on the front and rear surfaces of said multilayer core substrate is smaller than the thickness of the conductive layer of the inner layer.

Claim 9 (Original): A multilayer printed wiring board in which interlayer insulation layer and conductive layer are formed on multilayer core substrate composed of three or more layers, having a plurality of through holes for connecting the front surface with the rear surface and conductive layers on the front and rear surfaces and conductive layer in the inner layer so as to achieve electric connection through via holes,

said a plurality of through holes being composed of a plurality of power source through holes, a plurality of grounding through holes and a plurality of signal through holes connected electrically to a power source circuit or a grounding circuit or a signal circuit of an IC chip,

when said power source through holes pass through the grounding conductive layer of the inner layer in the multilayer core substrate, of the plurality of power source through holes, at least a power source through hole just below the IC having no conductive circuit extending from the power source through hole in the grounding conductive layer.

Claim 10 (Original): A multilayer printed wiring board in which interlayer insulation layer and conductive layer are formed on multilayer core substrate composed of three or more layers, having a plurality of through holes for connecting the front surface with the rear surface and conductive layers on the front and rear surfaces and conductive layer in the inner layer so as to achieve electric connection through via holes,

said a plurality of through holes being composed of a plurality of power source through holes, a plurality of grounding through holes and a plurality of signal through holes connected electrically to a power source circuit or a grounding circuit or a signal circuit of an IC chip,

when said grounding through holes pass through the power source conductive layer of the inner layer in the multilayer core substrate, of the plural grounding through holes, at least

a grounding through hole just below the IC having no conductive circuit extending from the grounding through hole in the power source conductive layer.

Claim 11 (Currently Amended): A multilayer printed wiring board in which interlayer insulation layer and conductive layer are formed on a multilayer core substrate composed of four or more layers, having a plurality of through holes for connecting the front and rear surfaces and conductive layers on the front and rear surfaces and conductive layer in the inner layer so as to achieve electric connection through via holes,

said multilayer printed wiring board having the power source through holes described in claim 9 ~~and the grounding through holes described in claim 10.~~

Claim 12 (Original): A multilayer printed wiring board in which interlayer insulation layer and conductive layer are formed on a multilayer core substrate composed of three or more layers, having a plurality of through holes for connecting the front and rear surfaces and conductive layers on the front and rear surfaces and conductive layer in the inner layer so as to achieve electric connection through via holes,

said a plurality of through holes being composed of a plurality of power source through holes, a plurality of grounding through holes and a plurality of signal through holes connected electrically to a power source circuit or a grounding circuit or a signal circuit of an IC chip,

when said power source through holes pass through the grounding conductive layer of the inner layer in the multilayer core substrate, of the plurality of power source through holes, 70% or more power source through holes having no conductive circuit extending from the power source through hole in the grounding conductive layer.

Claim 13 (Original): A multilayer printed wiring board in which interlayer insulation layer and conductive layer are formed on a multilayer core substrate composed of three or more layers, having a plurality of through holes for connecting the front and rear surfaces and conductive layers on the front and rear surfaces and conductive layer in the inner layer so as to achieve electric connection through via holes,

said a plurality of through holes being composed of a plurality of power source through holes, a plurality of grounding through holes and a plurality of signal through holes connected electrically to a power source circuit or a grounding circuit or a signal circuit of an IC chip,

when said grounding through holes pass through the power source conductive layer of the inner layer in the multilayer core substrate, of the plurality of grounding through holes, 70% or more grounding through holes having no conductive circuit extending from the grounding through hole in the power source conductive layer.

Claim 14 (Currently Amended): A multilayer printed wiring board in which interlayer insulation layer and conductive layer are formed on a multilayer core substrate composed of four or more layers, having a plurality of through holes for connecting the front and rear surfaces and conductive layers on the front and rear surfaces and conductive layer in the inner layer so as to achieve electric connection through via holes,

said multilayer printed wiring board having the power source through holes described in claim 12 ~~and the grounding through holes described in claim 13.~~

Claim 15 (Currently Amended): The multilayer printed wiring board according to ~~any one of claims 9-14~~ claim 9 wherein assuming that the sum of the thicknesses of the

power source conductive layers in said multilayer core substrate is α_1 and the thickness of the conductive layer on the interlayer insulation layer is α_2 , the relation of $\alpha_2 < \alpha_1 \leq 40\alpha_2$ exists.

Claim 16 (Original): The multilayer printed wiring board according to claim 15 wherein said α_1 is in a relation of $1.2\alpha_2 \leq \alpha_1 \leq 40\alpha_2$.

Claim 17 (Currently Amended): The multilayer printed wiring board according to ~~any one of claims 9-16~~ claim 9 wherein the conductive layers on the front and rear surfaces of said multilayer core substrate are power source conductive layers or grounding conductive layers.

Claim 18 (Currently Amended): The multilayer printed wiring board according to ~~any one of claims 9-16~~ claim 9 wherein said multilayer core substrate has a thick conductive layer in the inner layer and thin conductive layers on the front and rear surfaces.

Claim 19 (Currently Amended): The multilayer printed wiring board according to ~~any one of claims 9-16~~ claim 9 wherein the conductive layer of the inner layer in said multilayer core substrate is composed of two or more layers.

Claim 20 (Currently Amended): The multilayer printed wiring board according to ~~any one of claims 9-16~~ claim 9 wherein a capacitor is mounted on the surface thereof.

Claim 21 (Original): A multilayer printed wiring board in which interlayer insulation layer and conductive layer are formed on a multilayer core substrate composed of three or more layers, having a plurality of through holes for connecting the front and rear surfaces and

conductive layers on the front and rear surfaces and conductive layer in the inner layer so as to achieve electric connection through via holes,

said a plurality of through holes being composed of a plurality of power source through holes, a plurality of grounding through holes and a plurality of signal through holes connected electrically to a power source circuit or a grounding circuit or a signal circuit of an IC chip,

when said power source through holes pass through the grounding conductive layer of the inner layer in the multilayer core substrate, of the plurality of power source through holes, part of the power source through hole just below the IC having no conductive circuit extending from the power source through hole in the grounding conductive layer.

Claim 22 (Original): A multilayer printed wiring board in which interlayer insulation layer and conductive layer are formed on multilayer core substrate composed of three or more layers, having a plurality of through holes for connecting the front surface with the rear surface and conductive layers on the front and rear surfaces and conductive layer in the inner layer so as to achieve electric connection through via holes,

said a plurality of through holes being composed of a plurality of power source through holes, a plurality of grounding through holes and a plurality of signal through holes connected electrically to a power source circuit or a grounding circuit or a signal circuit of an IC chip,

when said grounding through holes pass through the power source conductive layer of the inner layer in the multilayer core substrate, of the plurality of grounding through holes, part of the grounding through hole just below the IC having no conductive circuit extending from the grounding through hole in the grounding conductive layer.

Claim 23 (Currently Amended): A multilayer printed wiring board in which interlayer insulation layer and conductive layer are formed on a multilayer core substrate composed of four or more layers, having a plurality of through holes for connecting the front and rear surfaces and conductive layers on the front and rear surfaces and conductive layer in the inner layer so as to achieve electric connection through via holes,

said multilayer printed wiring board having the power source through holes described in claim 21 ~~and the grounding through holes described in claim 22.~~

Claim 24 (Original): The multilayer printed wiring board according to claim 11 wherein the through holes just below the IC are disposed in the form of a grid or in a staggered fashion.

Claim 25 (Original): The multilayer printed wiring board according to claim 24 wherein the power source through holes and grounding through holes just below the IC are disposed alternately.

Claim 26 (Original): The multilayer printed wiring board according to claim 14 wherein the power source through hole having no conductive circuit extending from the power source through hole in the grounding conductive layer and the grounding through hole having no conductive circuit extending from the grounding through hole in the power source conductive layer are disposed in the form of a grid or in the staggered fashion just below the IC.

Claim 27 (Original): The multilayer printed wiring board according to claim 26 wherein the power source through hole having no conductive circuit extending from the

power source through hole in the grounding conductive layer and the grounding through hole having no conductive circuit extending from the grounding through hole in the power source conductive layer are disposed alternately.

Claim 28 (Original): The multilayer printed wiring board according to claim 23 wherein the power source through hole having no conductive circuit extending from the power source through hole in the grounding conductive layer and the grounding through hole having no conductive circuit extending from the grounding through hole in the power source conductive layer are disposed in the form of a grid or in the staggered fashion just below the IC.

Claim 29 (Original): The multilayer printed wiring board according to claim 28 wherein the power source through hole having no conductive circuit extending from the power source through hole in the grounding conductive layer and the grounding through hole having no conductive circuit extending from the grounding through hole in the power source conductive layer are disposed alternately.